

L Number	Hits	Search Text	DB	Time stamp
1	591015	(plate or board or substrate or article) near5 (resin\$5 or polymer\$5 or plastic or polyimide or non\$2conduct\$8 or insulat\$8 or epoxy)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03 10:46
2	129791	((plate or board or substrate or article) near5 (resin\$5 or polymer\$5 or plastic or polyimide or non\$2conduct\$8 or insulat\$8 or epoxy)) and ((plate or board or substrate or article) near5 (via\$3 or hole\$3 or opening\$3 or trench\$3 or recess\$3 or cavit\$6))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03 10:47
3	10	"13" and (electroless\$3 near15 (via\$3 or hole\$3 or opening\$3 or trench\$3 or recess\$3 or cavit\$6))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03 10:53
4	1851	((plate or board or substrate or article) near5 (resin\$5 or polymer\$5 or plastic or polyimide or non\$2conduct\$8 or insulat\$8 or epoxy)) and ((plate or board or substrate or article) near5 (via\$3 or hole\$3 or opening\$3 or trench\$3 or recess\$3 or cavit\$6))) and (electroless\$3 near15 (via\$3 or hole\$3 or opening\$3 or trench\$3 or recess\$3 or cavit\$6))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03 10:53
5	951	((plate or board or substrate or article) near5 (resin\$5 or polymer\$5 or plastic or polyimide or non\$2conduct\$8 or insulat\$8 or epoxy)) and ((plate or board or substrate or article) near5 (via\$3 or hole\$3 or opening\$3 or trench\$3 or recess\$3 or cavit\$6))) and (electroless\$3 near15 (via\$3 or hole\$3 or opening\$3 or trench\$3 or recess\$3 or cavit\$6))) and ((electroplat\$10 or electrodeposit\$10 or electroly\$10 or electrochem\$10) near15 (via\$3 or hole\$3 or opening\$3 or trench\$3 or recess\$3 or cavit\$6))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03 10:54
6	498	((plate or board or substrate or article) near5 (resin\$5 or polymer\$5 or plastic or polyimide or non\$2conduct\$8 or insulat\$8 or epoxy)) and ((plate or board or substrate or article) near5 (via\$3 or hole\$3 or opening\$3 or trench\$3 or recess\$3 or cavit\$6))) and (electroless\$3 near15 (via\$3 or hole\$3 or opening\$3 or trench\$3 or recess\$3 or cavit\$6))) and ((electroplat\$10 or electrodeposit\$10 or electroly\$10 or electrochem\$10) near15 (via\$3 or hole\$3 or opening\$3 or trench\$3 or recess\$3 or cavit\$6))) and wiring	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03 10:54
7	135	((plate or board or substrate or article) near5 (resin\$5 or polymer\$5 or plastic or polyimide or non\$2conduct\$8 or insulat\$8 or epoxy)) and ((plate or board or substrate or article) near5 (via\$3 or hole\$3 or opening\$3 or trench\$3 or recess\$3 or cavit\$6))) and (electroless\$3 near15 (via\$3 or hole\$3 or opening\$3 or trench\$3 or recess\$3 or cavit\$6))) and ((electroplat\$10 or electrodeposit\$10 or electroly\$10 or electrochem\$10) near15 (via\$3 or hole\$3 or opening\$3 or trench\$3 or recess\$3 or cavit\$6))) and wiring) and polish\$10	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03 12:00

9	11419	solder adj balls	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03 12:06
10	4372	((plate or board or substrate or article) near5 (resin\$5 or polymer\$5 or plastic or polyimide or non\$2conduct\$8 or insulat\$8 or epoxy)) and (solder adj balls)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03 12:07
11	4009	((plate or board or substrate or article) near5 (resin\$5 or polymer\$5 or plastic or polyimide or non\$2conduct\$8 or insulat\$8 or epoxy)) and (solder adj balls)) and (via\$3 or trench\$3 or hole\$3 or opening\$3 or recess\$3 or groove\$3 or cavit\$8)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03 12:07
12	1799	((plate or board or substrate or article) near5 (resin\$5 or polymer\$5 or plastic or polyimide or non\$2conduct\$8 or insulat\$8 or epoxy)) and (solder adj balls)) and (via\$3 or trench\$3 or hole\$3 or opening\$3 or recess\$3 or groove\$3 or cavit\$8)) and wiring	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03 12:09
13	1496	((plate or board or substrate or article) near5 (resin\$5 or polymer\$5 or plastic or polyimide or non\$2conduct\$8 or insulat\$8 or epoxy)) and (solder adj balls)) and (via\$3 or trench\$3 or hole\$3 or opening\$3 or recess\$3 or groove\$3 or cavit\$8)) and wiring) and pad\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03 12:08
15	93	((plate or board or substrate or article) near5 (resin\$5 or polymer\$5 or plastic or polyimide or non\$2conduct\$8 or insulat\$8 or epoxy)) and (solder adj balls)) and (via\$3 or trench\$3 or hole\$3 or opening\$3 or recess\$3 or groove\$3 or cavit\$8)) and wiring) and pad\$3) and (press\$2forming or (injection adj mold\$5))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03 12:09
16	90	((plate or board or substrate or article) near5 (resin\$5 or polymer\$5 or plastic or polyimide or non\$2conduct\$8 or insulat\$8 or epoxy)) and (solder adj balls)) and (via\$3 or trench\$3 or hole\$3 or opening\$3 or recess\$3 or groove\$3 or cavit\$8)) and wiring) and pad\$3) and (press\$2forming or (injection adj mold\$5))) not (((plate or board or substrate or article) near5 (resin\$5 or polymer\$5 or plastic or polyimide or non\$2conduct\$8 or insulat\$8 or epoxy)) and ((plate or board or substrate or article) near5 (via\$3 or hole\$3 or opening\$3 or trench\$3 or recess\$3 or cavit\$6))) and (electroless\$3 near15 (via\$3 or hole\$3 or opening\$3 or trench\$3 or recess\$3 or cavit\$6))) and ((electroplat\$10 or electrodeposit\$10 or electroly\$10 or electrochem\$10) near15 (via\$3 or hole\$3 or opening\$3 or trench\$3 or recess\$3 or cavit\$6))) and wiring) and polish\$10)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03 12:09